

ABSTRACT

A method and apparatus for treating an electroless plating solution is provided. The apparatus includes a reaction vessel, a cathode and an anode disposed in the interior of the reaction vessel and in electrical communication with a power source, a drain disposed in the reaction vessel, and a nozzle in fluid communication with the drain, disposed in the  
5 reaction vessel such that the nozzle and the drain are separated by the cathode and the anode. The method includes disposing an electroless plating solution in the reaction vessel, recirculating the plating solution through the reaction vessel by draining the plating solution from the reaction vessel and subsequently re-injecting the plating solution into the reaction vessel through the nozzle. A current is driven through the anode and  
10 cathode to oxidize reducing agents in the liquid and plate out the metal as the elemental metal.